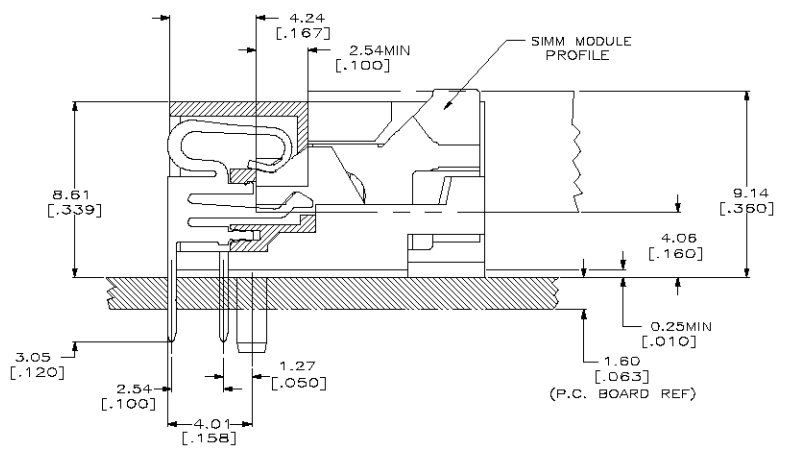
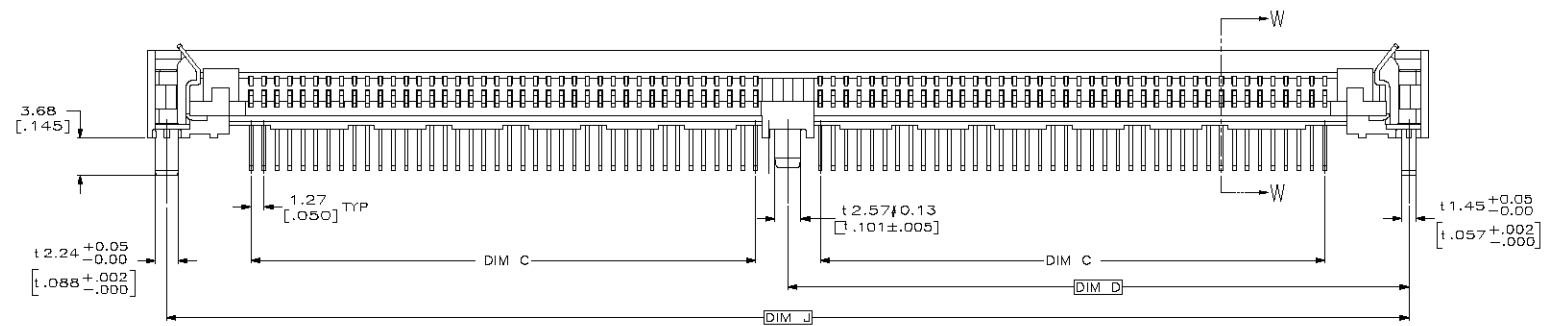
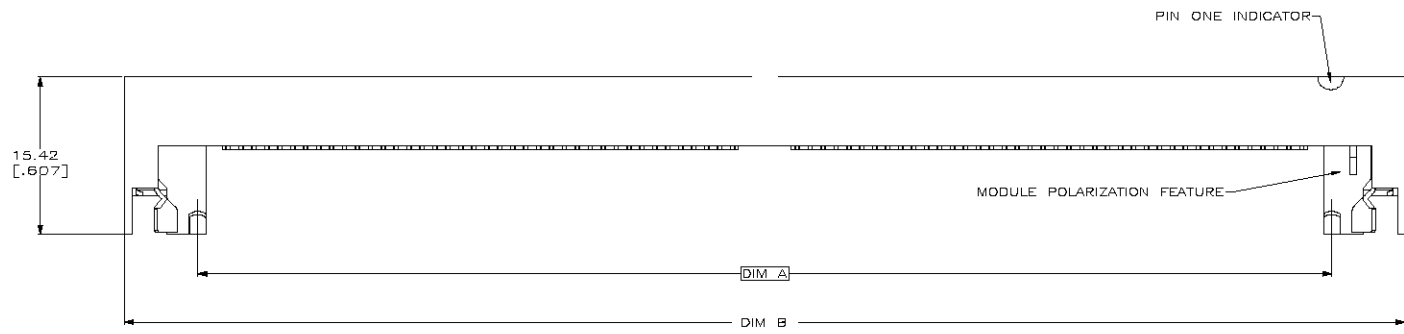


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0		RELEASED	ECO-95-001062	ZEMARON	W.K. I.E.

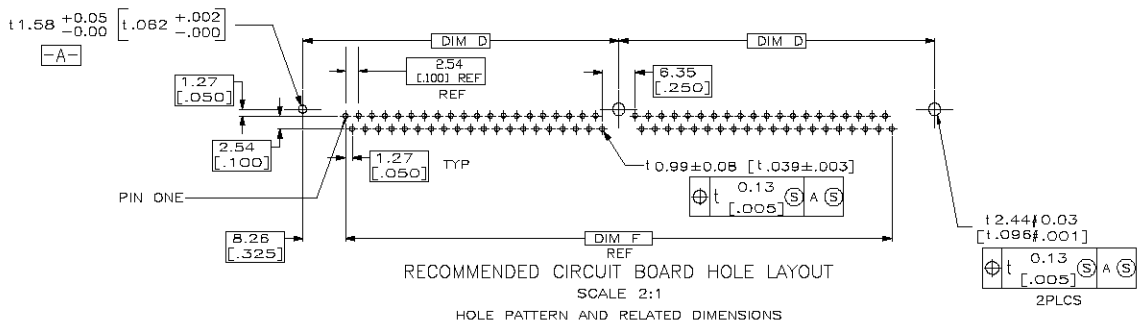


SECTION W-W
 SCALE 8:1

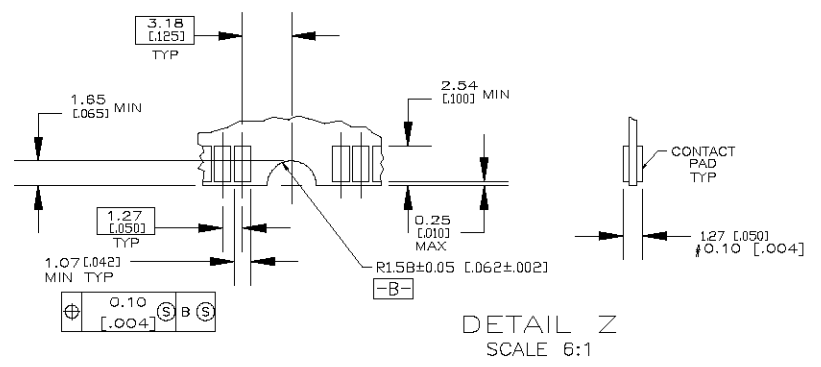
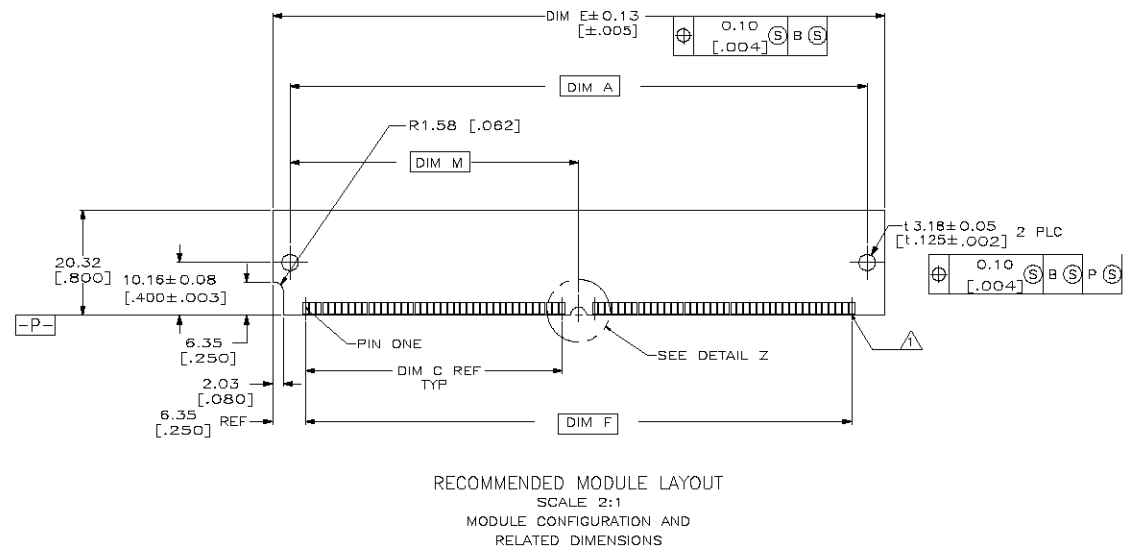
THIS DRAWING IS A CONTROLLED DOCUMENT.		DESIGNER	DATE	APPROVED	DATE	Amp Electronic Corporation mt. pro. pa 17932	
ENGINEER	DESIGNED BY	DESIGNED BY	DATE	APPROVED	DATE	SIMM II RTANG 1.27[.050] 1.27 [.050] CR ASSY 4.06[±.160] HEIGHT	
0 P.L.C. ± - 1 P.L.C. ± - 2 P.L.C. ± - 3 P.L.C. ± ±.1(1.000) 4 P.L.C. ± ± - 5 P.L.C. ± ± -	DRAWN BY CHECKED BY APPROVED BY	DRAWING NO 00779	SIZE A1	DATE CODE C-5382482	SHEET 4:1	OF 2	RESTRICTED TO 0
INTERNAL HSC-GLASS REINF		FRESH		CUSTOMER DRAWING			

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REVISONS		DATE	BY	APP
GP	00			
DESCRIPTION				
SEE SHEET 1				



- 1. FOR OPTIMUM PERFORMANCE, CONTACT PAD PLATING SHOULD BE SMOOTH AND FLAT. COPPER CONTACT PADS ARE TO BE OVERPLATED WITH .00127[.000050] MIN THK NICKEL FOLLOWED WITH .00254[.000100] MIN THK TIN PLATING.
- 2. 0.00381 [.000150] MIN. THK TIN OVER 0.00127 [.000050] MIN. THK NICKEL OVER ENTIRE CONTACT.



50.60 [1.992]	111.76 [4.400]	95.25 [3.750]	107.95 [4.250]	55.88 [2.200]	44.45 [1.750]	115.57 [4.550]	101.19 [3.984]	72	7-5382482-2
DIM M	DIM J	DIM F	DIM E	DIM D	DIM C	DIM B	DIM A	POSN	PART NO.

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APPROVED FOR RELEASE BY: STEVEN YAO

DATE: 11/07/79

SCALE: 4:1

SHEET: 2 OF 2

REV: 0

CUSTOMER DRAWING

AMP Type Electronics Corporation
 mt. Joy, pa 17962

SIMM II, RTANG,
 1.27 [050] CENTERLINE ASSY
 4.06 [180] HGT

DATE: 11/07/79
 DRAWING NO: 5382482